THE CHINESE UNIVERSITY OF HONG KONG  
Office of Admissions and Financial Aid  

Innovation and Technology Scholarship 2019  

Information Sheet

The “Innovation and Technology Scholarship”, also named “創新科技獎學金” in Chinese, aims to provide recognition to outstanding undergraduates in universities in Hong Kong as well as opportunities to widen their international/Mainland exposure and gain industry experience. Twenty-five science undergraduates, to be nominated by the local universities and selected by an Awardee Selection Committee of the Scholarship, will each be awarded a scholarship of up to HKD150,000 for a series of learning programmes.

I. Components of the Scholarship

A. Financial Support for Overseas/Mainland Attachment Programme(s)

Awardees will be supported to attach to one or more overseas/Mainland universities/institutions between 1 June 2019 and 30 June 2020. At least one of the awardee’s trips must be longer than three weeks. Awardees will not be restricted by the number of trips and format of the programme(s) as long as the programme(s) is/are supported by the teaching staff of The Chinese University of Hong Kong (CUHK).

The Innovation and Technology Commission, HSBC, The Hongkong Federation of Youth Groups and CUHK do not have any arrangements with the overseas/Mainland universities/institutions designated by the Scholarship Secretariat (please refer to Appendix 1 for the List of Suggested Overseas / Mainland Universities) whereby awardees will be guaranteed admission despite the fact that CUHK has exchange programmes with some of these universities/institutions. Selected candidates are responsible for fulfilling all application procedures and admission requirements at overseas/Mainland universities/institutions of their choice from Appendix 1 and be offered a place subsequently. Candidates are, therefore, strongly advised to pay the closest attention to application procedures as soon as possible and selected candidates should secure acceptance independent of the Innovation and Technology Commission, HSBC, The Hongkong Federation of Youth Groups and CUHK. Universities/institutions that are not on the list may be considered if there are sufficient justifications.

B. Mentorship Programme

Each awardee will be assigned to a mentor, who is an outstanding personality in his/her related field of study as far as possible. The mentor will provide advice and guidance to the awardee not only throughout the Scholarship period but hopefully thereafter.

C. Service Project Programme

Each awardee will be invited to participate in community activities relating to innovation and technology, e.g. participating in educational activities organised for local primary and secondary school students to arouse their interest in science and technology.
The Scholarship Secretariat has advised that the students should reserve some time for the Service Project Programme, of which details will be given to the selected candidates by the Scholarship Secretariat direct.

D. Local Internship Programme [Optional]

Awardees who opt to undertake the Local Internship Programme under the Scholarship will be given an opportunity to work as an intern for 4-12 weeks in a local technology company, organisation or government department relevant to his/her field of study as far as possible. An internship allowance of HKD3,000 per week (on the basis of five working days per week) will be offered to the awardee during the internship period. The amount will be drawn from the total scholarship budget.

II. Eligibility and selection criteria

The Scholarship is open to **full-time, non-final-year undergraduates** who meet the following criteria*:

1. Be registered CUHK students in the tenure year of the scholarship;
2. Hong Kong Permanent Residents with the right of abode in Hong Kong.
3. Undertaking a science-related degree funded by the University Grants Committee (UGC). In general they cover (i) Sciences; (ii) Engineering and Technology; and (iii) Medicine and Health professions. **Only students taking BSc, BEng, MBChB, BNurs, BPharm or Bachelor of Chinese Medicine programmes are eligible.**
4. Preferably a cumulative GPA of 3.30 (or equivalent) or above up to Term 1 of 2018/19 #.
5. A minimum total TOEFL (Internet-based test) score of 90 with scores for individual sections not lower than 21 on reading, 22 on listening, 21 on speaking, and 17 on writing; or a minimum IELTS (Academic test) overall band score of 6.5, with no component below 6.0. These are irrespective of overseas universities’ requirements. **All tests must have been taken on or after 1 February 2017.**
6. Have passion in innovation and technology, and intention of pursuing this as a career.
7. Well-rounded, have participated in extra-curricular and/or community service activities.
8. Able to display tremendous upside potential and benefit the most from the Scholarship.
9. Willing to serve the community and have a strong commitment to Hong Kong.
10. Possess good communication skills.
11. Have not previously received an award under this Scholarship.

* The Scholarship Secretariat reserves the right to accept or decline any application.
# Though the academic results for Term 1 of 2018/19 are not available yet at the time of application, student should still submit his/her scholarship application if he/she would like to be considered. For those cumulative GPA (up to Term 1 of 2018/19) is eventually below 3.30, they need to seek an additional recommendation from the Faculty/Department for their application.

III. Selection procedures

1. The eligible undergraduates who are interested in the Scholarship should fill in the application form and submit it together with all supporting documents to their Faculty Office on or before 27 December 2018. Please check with the respective Faculty for the exact submission location. Late or incomplete applications will not be considered. Please refer to the “Checklist of Supporting Documents”, which is provided
by the Office of Admissions and Financial Aid, for the supporting documents to be submitted by the candidates.

(2) Applicants should work out their preferred packages for the Overseas/Mainland Attachment Programme and submit the proposed plans with the application.

(3) Suitable candidates nominated by the Faculties are required to attend a selection interview to be held in and by the University in late January 2019. Shortlisted candidates will be invited to attend an interview to be held by the Awardee Selection Committee of the Scholarship in Hong Kong in late February/early March 2019. Candidates must attend all interviews in person. No phone interview/ interview by skype will be arranged. The cost of travel to the interviews will not be reimbursed to the candidates.

(4) Upon selection by the Awardee Selection Committee, successful candidates will be notified by the Scholarship Secretariat through CUHK by late March 2019.

(5) Successful candidates are expected, unless with exceptional reason, to attend the Award Presentation Ceremony to be held in April 2019.

(6) Programmes under the Scholarship will be undertaken between 1 June 2019 and 30 June 2020; all the expenditure for the programmes must be incurred within the period.

(7) The decision of the University and/or the Awardee Selection Committee of the Scholarship is final and not subject to review, and the reasons for granting or refusing to offer an award will not be given.

IV. Scholarship value and payment method

The maximum value for each scholarship is HKD150,000. A budget breakdown for each awardee will be worked out and submitted when the candidate is successfully selected.

The scholarship amount for each awardee will cover:

(1) Tuition/course fees and college fees for the host university
(2) Cost of accommodation outside Hong Kong
(3) Subsistence allowance for the period outside Hong Kong
(4) Economy return air-tickets to/from the host’s city
(5) Visa application fees
(6) Insurance
(7) Books and necessary supplies
(8) Internship allowance of HKD3,000 per week (on the basis of five working days per week).

The scholarship will be granted based on the realistic projection of costs provided by individual awardees, to be checked and endorsed by CUHK. The Scholarship Secretariat will release the approved scholarship amount for the Overseas/Mainland Attachment Programme to individual awardees through CUHK.

V. Terms and conditions for acceptance of the Scholarship

The Scholarship will be awarded subject to the following conditions:
(1) The awardee has to abide by any conditions laid down for the Scholarship Secretariat.

(2) The awardee will be required to participate in a service project programme, such as acting as an ambassador at local schools to arouse students’ interest in science and technology for an agreed number of hours; helping to organise activities at the Hong Kong Federation of Youth Groups Centre for Creative Science and Technology, etc.

(3) The awardee will be required to participate in the Scholarship’s promotional events and other related activities, e.g. award presentation ceremony and media interviews.

(4) The awardee will be required to submit a report (around 3,000 words) to the Scholarship Secretariat after completion of the Scholarship on his/her experience in the:
   - Overseas/Mainland Attachment Programme;
   - Mentorship Programme;
   - Service Project Programme;
   - Local Internship Programme (if applicable); and
   - How the Scholarship has benefited him/her and whether he/she would like to suggest any areas of improvement.

(5) The awardee will also be required to submit reference documents by the overseas/Mainland university/institution and internship supervisor upon completion of the programmes.

(6) The awardee accepts that the Scholarship may be terminated at any time if and when his/her performance is considered unsatisfactory or when he/she for any reason withdraws from his/her current degree programme.

(7) Unless justifications can be provided, full/pro-rata refund of the scholarship by the awardee will be necessary if he/she cannot fulfill the conditions stated by the Scholarship or fails to complete all programmes.

VI. Handling of information and personal data

The information and personal data provided in the application form will be used and/or disclosed by CUHK and/or the Scholarship Secretariat to relevant parties to process the application/nomination as well as for related purposes, such as conducting selection interviews, monitoring of progress, etc.

VII. Enquiries

Please contact the Scholarships and Financial Aid Section, Office of Admissions and Financial Aid at sfas@cuhk.edu.hk or 3943 7204.

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List of Suggested Overseas / Mainland Universities

IMPORTANT: The Scholarship Secretariat does not have any arrangement with the below listed universities whereby awardees will be guaranteed admission. Awardees are advised to pay the closest attention to application procedures and timeline to secure acceptance independent of the Secretariat. Should the awardees wish to select universities/institutions which are not on the list, it can be considered provided that there are sufficient justifications.

**Australia**
- Australian National University
- Monash University
- University of Melbourne
- University of New South Wales
- University of Queensland
- University of Sydney
- University of Western Australia

**China**
- Beihang University
- Beijing Institute of Technology
- Fudan University
- Harbin Institute of Technology
- Huazhong University of Science and Technology
- Nanjing University
- Nankai University
- Peking University
- Shanghai Jiao Tong University
- Tongji University
- Tsinghua University
- University of Science and Technology of China
- Wuhan University
- Xian Jiao Tong University
- Zhejiang University
Denmark
- Aalborg University
- Aarhus University
- Technical University of Denmark
- University of Copenhagen

France
- Ecole Normale Superieure, Paris
- Ecole Polytechnique
- Pierre and Marie Curie University

Germany
- Eberhard Karls University, Tübingen
- Humboldt University of Berlin
- Ludwig-Maximilians-Universität München
- Ruprecht-Karls-Universität Heidelberg
- RWTH Aachen University
- Technical University of Berlin
- Technical University of Munich
- Technische Universität of Darmstadt
- University of Freiburg
- University of Göttingen
- University of Hamburg
- University of Munich
- University of Stuttgart

Korea
- Korea Advanced Institute of Science and Technology
- Korea University
- Pohang University of Science And Technology
- Seoul National University

Netherlands
- Delft University of Technology
- Erasmus University Rotterdam
- University of Amsterdam

Sweden
- Chalmers University of Technology
- Lund University
- Karolinska Institute
- KTH Royal Institute of Technology
- Stockholm University

Switzerland
- École Polytechnique Fédérale de Lausanne
- ETH Zurich - Swiss Federal Institute of Technology Zurich
- University of Basel
- University of Geneva
- University of Lausanne
- University of Zurich

UK / Ireland
- Cardiff University
- Durham University
- Imperial College London
- King’s College London
UK / Ireland (cont.)
- London School of Hygiene and Tropical Medicine
- Newcastle University
- Queen Mary University of London
- Trinity College Dublin, The University of Dublin
- University College London
- University of Aberdeen
- University of Bath
- University of Birmingham
- University of Bristol
- University of Cambridge
- University of Edinburgh
- University of Glasgow
- University of Leeds
- University of Liverpool
- University of Manchester
- University of Nottingham
- University of Oxford
- University of Sheffield
- University of St Andrews
- University of Warwick
- University of York

USA
- Baylor College of Medicine
- Boston University
- Brown University
- California Institute of Technology
- Carnegie Mellon University
- Columbia University
- Cornell University
- Dartmouth College
- Duke University
- Emory University
- Georgia Institute of Technology
- Harvard University
- Johns Hopkins University
- Massachusetts Institute of Technology
- Michigan State University
- New York University
- Northwestern University
- Ohio State University
- Pennsylvania State University
- Princeton University
- Rice University
- Rockefeller University
- Stanford University
- Stony Brook University
- Texas A&M University
- Tufts University
- University of Arizona
- University of California, Berkeley
- University of California, Davis
- University of California, Irvine
- University of California, Los Angeles
- University of California, San Diego
- University of California, San Francisco
- University of California, Santa Barbara
- University of Chicago
- University of Colorado Boulder
- University of Florida
- University of Illinois, Chicago
USA (cont.)
- University of Illinois, Urbana-Champaign
- University of Maryland College Park
- University of Michigan
- University of Minnesota
- University of North Carolina, Chapel Hill
- University of Pennsylvania
- University of Pittsburgh
- University of Southern California
- University of Texas at Austin
- University of Virginia
- University of Washington
- University of Wisconsin-Madison
- Vanderbilt University
- Washington University in St. Louis
- Yale University

Other countries / regions
- Universidad de Buenos Aires (Argentina)
- Vienna University of Technology (Austria)
- Katholieke Universiteit Leuven (Belgium)
- Indian Institute of Technology Delhi (India)
- Polytechnic University of Milan (Italy)
- University of Auckland (New Zealand)
- University of Bergen (Norway)
- Lomonosov Moscow State University (Russia)
- Nanyang Technological University, Singapore (Singapore)
- National University of Singapore (Singapore)
- University of Barcelona (Spain)
- National Taiwan University (Taiwan)
- National Tsing Hua University (Taiwan)